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#### Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	LINbus, SCI, SPI
Peripherals	LVD, POR, PWM
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
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#### Memory

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
	Configuration Register 2	Read:	0	0	0	0	в	TMBCLK-	OSCENIN-	ESCIBD-
\$001E	(CONFIG2) <sup>(1)</sup> See page 80	Write:					- 11	SEL	STOP	SRC
	dee page ou.		0	0	0	0	0	0	0	1
\$001F	Configuration Register 1		COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVI5OR3 (Note 1)	SSREC	STOP	COPD
	See page 80.	Reset:	0	0	0	0	0	0	0	0
1. One-ti	me writable register after each	reset, ex	cept LVI5OR	3 bit. LVI5OF	3 bit is only r	eset via POR	(power-on re	set).		
	Timer 1 Status and Control	Read:	TOF	TOIL	TOTOD	0	0	<b>B</b> 00	<b>D</b> 04	<b>D</b> 00
\$0020	Register (T1SC)	Write:	0	TOIE	ISTOP	TRST		P52	P51	P50
	See page 231.	Reset:	0	0	1	0	0	0	0	0
	Timer 1 Counter	Read:	Bit 15	14	13	12	11	10	9	Bit 8
\$0021	Register High (T1CNTH)	Write:								
	See page 232.	Reset:	0	0	0	0	0	0	0	0
	Timer 1 Counter	Read:	Bit 7	6	5	4	3	2	1	Bit 0
\$0022	Register Low (T1CNTL)	Write:								
	See page 232.	Reset:	0	0	0	0	0	0	0	0
\$0023	Timer 1 Counter Modulo Register High (T1MODH)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
	See page 233.	Reset:	1	1	1	1	1	1	1	1
\$0024	Timer 1 Counter Modulo Register Low (T1MODL)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
	See page 233.	Reset:	1	1	1	1	1	1	1	1
\$0025	Timer 1 Channel 0 Status and Control Register (T1SC0)	Read: Write:	CH0F 0	CH0IE	MS0B	MS0A	ELS0B	ELS0A	TOV0	CH0MAX
	See page 233.	Reset:	0	0	0	0	0	0	0	0
\$0026	Timer 1 Channel 0 Register High (T1CH0H)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
	See page 236.	Reset:				Indeterminat	te after reset			
\$0027	Timer 1 Channel 0 Register Low (T1CH0L)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
	See page 236.	Reset:				Indetermina	te after reset			
	Timer 1 Channel 1 Status and	Read:	CH1F		0	MC1A			TO\/1	
\$0028	Control Register (T1SC1)	Write:	0	CHIE		IVIS IA	ELGID	ELSTA	1001	CHIMAN
	See page 234.	Reset:	0	0	0	0	0	0	0	0
				= Unimplem	nented	R	= Reserved	U = Una	ffected	

Figure 2-2. Control, Status, and Data Registers (Sheet 4 of 8)



Memory

# 2.5 Random-Access Memory (RAM)

Addresses \$0040 through \$043F are RAM locations. The location of the stack RAM is programmable. The 16-bit stack pointer allows the stack to be anywhere in the 64-Kbyte memory space.

## NOTE

For correct operation, the stack pointer must point only to RAM locations.

Within page zero are 192 bytes of RAM. Because the location of the stack RAM is programmable, all page zero RAM locations can be used for I/O control and user data or code. When the stack pointer is moved from its reset location at \$00FF out of page zero, direct addressing mode instructions can efficiently access all page zero RAM locations. Page zero RAM, therefore, provides ideal locations for frequently accessed global variables.

Before processing an interrupt, the CPU uses five bytes of the stack to save the contents of the CPU registers.

## NOTE

For M6805 compatibility, the H register is not stacked.

During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements during pushes and increments during pulls.

# NOTE

Be careful when using nested subroutines. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.

# 2.6 FLASH Memory (FLASH)

This subsection describes the operation of the embedded FLASH memory. This memory can be read, programmed, and erased from a single external supply. The program, erase, and read operations are enabled through the use of an internal charge pump. It is recommended that the user utilize the FLASH programming routines provided in the on-chip ROM, which are described more fully in a separate Freescale application note.

# 2.6.1 Functional Description

The FLASH memory is an array of 15,872 bytes with an additional 36 bytes of user vectors and one byte of block protection. *An erased bit reads as a 1 and a programmed bit reads as a 0*. Memory in the FLASH array is organized into two rows per page basis. For the 16-K word by 8-bit embedded FLASH memory, the page size is 64 bytes per page and the row size is 32 bytes per row. Hence the minimum erase page size is 64 bytes and the minimum program row size is 32 bytes. Program and erase operation operations are facilitated through control bits in FLASH control register (FLCR). Details for these operations appear later in this section.

The address ranges for the user memory and vectors are:

- \$C000-\$FDFF; user memory
- \$FE08; FLASH control register
- \$FF7E; FLASH block protect register
- \$FFDC-\$FFFF; these locations are reserved for user-defined interrupt and reset vectors



# 4.3.1 Crystal Oscillator Circuit

The crystal oscillator circuit consists of an inverting amplifier and an external crystal. The OSC1 pin is the input to the amplifier and the OSC2 pin is the output. The SIMOSCEN signal from the system integration module (SIM) or the OSCSTOPENB bit in the CONFIG register enable the crystal oscillator circuit.

The CGMXCLK signal is the output of the crystal oscillator circuit and runs at a rate equal to the crystal frequency. CGMXCLK is then buffered to produce CGMRCLK, the PLL reference clock.

CGMXCLK can be used by other modules which require precise timing for operation. The duty cycle of CGMXCLK is not guaranteed to be 50% and depends on external factors, including the crystal and related external components. An externally generated clock also can feed the OSC1 pin of the crystal oscillator circuit. Connect the external clock to the OSC1 pin and let the OSC2 pin float.

## 4.3.2 Phase-Locked Loop Circuit (PLL)

The PLL is a frequency generator that can operate in either acquisition mode or tracking mode, depending on the accuracy of the output frequency. The PLL can change between acquisition and tracking modes either automatically or manually.

### 4.3.3 PLL Circuits

The PLL consists of these circuits:

- Voltage-controlled oscillator (VCO)
- Reference divider
- Frequency prescaler
- Modulo VCO frequency divider
- Phase detector
- Loop filter
- Lock detector

The operating range of the VCO is programmable for a wide range of frequencies and for maximum immunity to external noise, including supply and CGM/XFC noise. The VCO frequency is bound to a range from roughly one-half to twice the center-of-range frequency,  $f_{VRS}$ . Modulating the voltage on the CGM/XFC pin changes the frequency within this range. By design,  $f_{VRS}$  is equal to the nominal center-of-range frequency,  $f_{NOM}$ , (38.4 kHz) times a linear factor, L, and a power-of-two factor, E, or  $(L \times 2^E) f_{NOM}$ .

CGMRCLK is the PLL reference clock, a buffered version of CGMXCLK. CGMRCLK runs at a frequency,  $f_{RCLK}$ , and is fed to the PLL through a programmable modulo reference divider, which divides  $f_{RCLK}$  by a factor, R. The divider's output is the final reference clock, CGMRDV, running at a frequency,  $f_{RDV} = f_{RCLK}/R$ . With an external crystal (30 kHz–100 kHz), always set R = 1 for specified performance. With an external high-frequency clock source, use R to divide the external frequency to between 30 kHz and 100 kHz.

The VCO's output clock, CGMVCLK, running at a frequency,  $f_{VCLK}$ , is fed back through a programmable prescale divider and a programmable modulo divider. The prescaler divides the VCO clock by a power-of-two factor P and the modulo divider reduces the VCO clock by a factor, N. The dividers' output is the VCO feedback clock, CGMVDV, running at a frequency,  $f_{VDV} = f_{VCLK}/(N \times 2^P)$ . (See 4.3.6 Programming the PLL for more information.)



# 4.5 CGM Registers

These registers control and monitor operation of the CGM:

- PLL control register (PCTL) see 4.5.1 PLL Control Register.
- PLL bandwidth control register (PBWC) see 4.5.2 PLL Bandwidth Control Register.
- PLL multiplier select register high (PMSH) see 4.5.3 PLL Multiplier Select Register High.
- PLL multiplier select register low (PMSL) see 4.5.4 PLL Multiplier Select Register Low.
- PLL VCO range select register (PMRS) see 4.5.5 PLL VCO Range Select Register.
- PLL reference divider select register (PMDS) see 4.5.6 PLL Reference Divider Select Register.

Figure 4-3 is a summary of the CGM registers.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0	
\$0036	PLL Control Register (PCTL)		PLLIE	PLLF	PLLON	BCS	PRE1	PRE0	VPR1	VPR0	
	000 page 70.	Reset:	0	0	1	0	0	0	0	0	
	PLL Bandwidth Control Reg-	Read:		LOCK	ACO	0	0	0	0	Р	
\$0037	ister (PBWC)	Write:	AUTO		ACQ					n	
	See page 72.	Reset:	0	0	0	0	0	0	0	0	
	PLL Multiplier Select High	Read:	0	0	0	0	MUU 11	MUL 10	MULO	MULO	
\$0038	Register (PMSH) See page 73.	Write:					MOLTI	WOLTO	WICE5	NUCLO	
		Reset:	0	0	0	0	0	0	0	0	
\$0039	PLL Multiplier Select Low Register (PMSL)	Read: Write:	MUL7	MUL6	MUL5	MUL4	MUL3	MUL2	MUL1	MUL0	
	See page 73.	Reset:	0	1	0	0	0	0	0	0	
	PLL VCO Select Range	Read:	VBS7	VBS6	VBS5	VBS4	VBS3	VBS2	VBS1	VBS0	
\$003A	Register (PMRS)	Write:	1107	1100	1100	1104	1100	VIIOZ	VIIOT	VIIOO	
	See page 74.	Reset:	0	1	0	0	0	0	0	0	
	PLL Reference Divider	Read:	0	0	0	0	BD83	8082		BDSU	
\$003B	Select Register (PMDS)	Write:					11000	11002	1001	1000	
	See page 74.	Reset:	0	0	0	0	0	0	0	1	

NOTES:

1. When AUTO = 0, PLLIE is forced clear and is read-only.

2. When AUTO = 0, PLLF and LOCK read as clear.

3. When AUTO = 1,  $\overline{ACQ}$  is read-only.

4. When PLLON = 0 or VRS7:VRS0 = \$0, BCS is forced clear and is read-only.

5. When PLLON = 1, the PLL programming register is read-only.

6. When BCS = 1, PLLON is forced set and is read-only.

= Unimplemented

= Reserved

R

Figure 4-3. CGM I/O Register Summary



#### **Clock Generator Module (CGM)**

# 4.7.2 Stop Mode

If the OSCSTOPENB bit in the CONFIG register is cleared (default), then the STOP instruction disables the CGM (oscillator and phase locked loop) and holds low all CGM outputs (CGMXCLK, CGMOUT, and CGMINT).

If the STOP instruction is executed with the VCO clock, CGMVCLK, divided by two driving CGMOUT, the PLL automatically clears the BCS bit in the PLL control register (PCTL), thereby selecting the crystal clock, CGMXCLK, divided by two as the source of CGMOUT. When the MCU recovers from STOP, the crystal clock divided by two drives CGMOUT and BCS remains clear.

If the OSCSTOPENB bit in the CONFIG register is set, then the phase locked loop is shut off but the oscillator will continue to operate in stop mode.

# 4.7.3 CGM During Break Interrupts

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the SIM break flag control register (SBFCR) enables software to clear status bits during the break state. (See Chapter 15 System Integration Module (SIM).)

To allow software to clear status bits during a break interrupt, write a 1 to the BCFE bit. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect the PLLF bit during the break state, write a 0 to the BCFE bit. With BCFE at 0 (its default state), software can read and write the PLL control register during the break state without affecting the PLLF bit.

# 4.8 Acquisition/Lock Time Specifications

The acquisition and lock times of the PLL are, in many applications, the most critical PLL design parameters. Proper design and use of the PLL ensures the highest stability and lowest acquisition/lock times.

# 4.8.1 Acquisition/Lock Time Definitions

Typical control systems refer to the acquisition time or lock time as the reaction time, within specified tolerances, of the system to a step input. In a PLL, the step input occurs when the PLL is turned on or when it suffers a noise hit. The tolerance is usually specified as a percentage of the step input or when the output settles to the desired value plus or minus a percentage of the frequency change. Therefore, the reaction time is constant in this definition, regardless of the size of the step input. For example, consider a system with a 5 percent acquisition time tolerance. If a command instructs the system to change from 0 Hz to 1 MHz, the acquisition time is the time taken for the frequency to reach 1 MHz  $\pm$ 50 kHz. Fifty kHz = 5% of the 1-MHz step input. If the system is operating at 1 MHz and suffers a -100-kHz noise hit, the acquisition time is the time taken to return from 900 kHz to 1 MHz  $\pm$ 5 kHz. Five kHz = 5% of the 100-kHz step input.

Other systems refer to acquisition and lock times as the time the system takes to reduce the error between the actual output and the desired output to within specified tolerances. Therefore, the acquisition or lock time varies according to the original error in the output. Minor errors may not even be registered. Typical PLL applications prefer to use this definition because the system requires the output frequency to be within a certain tolerance of the desired frequency regardless of the size of the initial error.



**Configuration Register (CONFIG)** 



**Central Processor Unit (CPU)** 

Course				Effect					SS	de	pu	s
Form	Operation Description						n   7	6	ddre ode	bco	pera	/cle
			v	п	•	IN	2	C	Ă	ō	ō	С С
PULA	Pull A from Stack	$SP \leftarrow (SP + 1); Pull (A)$	-	-	-	-	-	-	INH	86		2
	Pull H from Stack	$SP \leftarrow (SP + 1); Pull (H)$	-	-	-	-	-	-		8A		2
PULX	Pull X from Stack	$SP \leftarrow (SP + 1); Pull(X)$	-	-	-	-	-	-		88	44	2
ROLA ROLX ROL <i>opr</i> ,X ROL ,X ROL <i>opr</i> ,SP	Rotate Left through Carry	C ← ← _ ← _ ← ← ← ← ← ← ← _ ← ← _ \oplus ← € € ← ← ← € € € €	ţ	_	_	1	ţ	ţ	INH INH IX1 IX SP1	49 59 69 79 9E69	ff ff	4 1 4 3 5
ROR <i>opr</i> RORA RORX ROR <i>opr</i> ,X ROR ,X ROR <i>opr</i> ,SP	Rotate Right through Carry	b7 b0	ţ	_	_	\$	ţ	ţ	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	4 1 1 4 3 5
RSP	Reset Stack Pointer	$SP \leftarrow \$FF$	-	-	-	-	-	-	INH	9C		1
RTI	Return from Interrupt	$\begin{array}{l} SP \leftarrow (SP) + 1; \ Pull \ (CCR) \\ SP \leftarrow (SP) + 1; \ Pull \ (A) \\ SP \leftarrow (SP) + 1; \ Pull \ (X) \\ SP \leftarrow (SP) + 1; \ Pull \ (PCH) \\ SP \leftarrow (SP) + 1; \ Pull \ (PCL) \end{array}$	ţ	ţ	ţ	1	ţ	ţ	INH	80		7
RTS	Return from Subroutine	$SP \leftarrow SP + 1$ ; Pull (PCH) $SP \leftarrow SP + 1$ ; Pull (PCL)	-	-	-	I	_	-	INH	81		4
SBC #opr SBC opr SBC opr SBC opr,X SBC opr,X SBC ,X SBC opr,SP SBC opr,SP	Subtract with Carry	$A \leftarrow (A) - (M) - (C)$	ţ	_	_	ţ	ţ	ţ	IMM DIR EXT IX2 IX1 IX SP1 SP2	A2 B2 C2 D2 E2 F2 9EE2 9ED2	ii dd hh II ee ff ff ee ff	23443245
SEC	Set Carry Bit	C ← 1	-	-	-	-	-	1	INH	99		1
SEI	Set Interrupt Mask	l ← 1	-	-	1	-	-	-	INH	9B		2
STA opr STA opr STA opr,X STA opr,X STA opr,SP STA opr,SP	Store A in M	M ← (A)	0	_	_	ţ	ţ	_	DIR EXT IX2 IX1 IX SP1 SP2	B7 C7 D7 E7 F7 9EE7 9ED7	dd hh II ee ff ff ee ff	3443245
STHX opr	Store H:X in M	$(M{:}M+1) \leftarrow (H{:}X)$	0	-	-	\$	\$	-	DIR	35	dd	4
STOP	Enable Interrupts, Stop Processing, Refer to MCU Documentation	$I \leftarrow 0$ ; Stop Processing	-	-	0	1	-	-	INH	8E		1
STX opr STX opr STX opr,X STX opr,X STX,X STX,X STX opr,SP STX opr,SP	Store X in M	M ← (X)	0	_	_	ţ	ţ	_	DIR EXT IX2 IX1 IX SP1 SP2	BF CF DF EF FF 9EEF 9EDF	dd hh II ee ff ff ee ff	344 324 5
SUB #opr SUB opr SUB opr SUB opr,X SUB opr,X SUB ,X SUB opr,SP SUB opr,SP	Subtract	A ← (A) – (M)	ţ	_	_	ţ	ţ	ţ	IMM DIR EXT IX2 IX1 IX SP1 SP2	A0 B0 C0 D0 E0 F0 9EE0 9ED0	ii dd hh II ee ff ff ee ff	2 3 4 4 3 2 4 5

Table 7-1.	Instruction	Set	Summarv	(Sheet 5	of 6)
			• • • • • • • • • • • • • • • • • • •	(0.000.0	••••



**Functional Description** 



Figure 8-2. IRQ Module Block Diagram

When an interrupt pin is both falling-edge and low-level triggered (MODE = 1), the interrupt remains set until both of these events occur:

- Vector fetch or software clear
- Return of the interrupt pin to 1

The vector fetch or software clear may occur before or after the interrupt pin returns to 1. As long as the pin is low, the interrupt request remains pending. A reset will clear the latch and the MODE control bit, thereby clearing the interrupt even if the pin stays low.

When set, the IMASK bit in the INTSCR mask all external interrupt requests. A latched interrupt request is not presented to the interrupt priority logic unless the IMASK bit is clear.

**NOTE** The interrupt mask (I) in the condition code register (CCR) masks all interrupt requests, including external interrupt requests.



Figure 8-3. IRQ I/O Register Summary



# Chapter 11 Low-Voltage Inhibit (LVI)

# 11.1 Introduction

This section describes the low-voltage inhibit (LVI) module, which monitors the voltage on the  $V_{DD}$  pin and can force a reset when the  $V_{DD}$  voltage falls below the LVI trip falling voltage,  $V_{TRIPF}$ .

# **11.2 Features**

Features of the LVI module include:

- Programmable LVI reset
- Selectable LVI trip voltage
- Programmable stop mode operation

# **11.3 Functional Description**

Figure 11-1 shows the structure of the LVI module. The LVI is enabled out of reset. The LVI module contains a bandgap reference circuit and comparator. Clearing the LVI power disable bit, LVIPWRD, enables the LVI to monitor  $V_{DD}$  voltage. Clearing the LVI reset disable bit, LVIRSTD, enables the LVI module to generate a reset when  $V_{DD}$  falls below a voltage,  $V_{TRIPF}$ . Setting the LVI enable in stop mode bit, LVISTOP, enables the LVI to operate in stop mode. Setting the LVI 5-V or 3-V trip point bit, LVISOR3, enables the trip point voltage,  $V_{TRIPF}$ , to be configured for 5-V operation. Clearing the LVI5OR3 bit enables the trip point voltage,  $V_{TRIPF}$ , to be configured for 3-V operation. The actual trip points are shown in Chapter 20 Electrical Specifications.

### NOTE

After a power-on reset (POR) the LVI's default mode of operation is 3 V. If a 5-V system is used, the user must set the LVI5OR3 bit to raise the trip point to 5-V operation. Note that this must be done after every power-on reset since the default will revert back to 3-V mode after each power-on reset. If the  $V_{DD}$  supply is below the 5-V mode trip voltage but above the 3-V mode trip voltage when POR is released, the part will operate because  $V_{TRIPF}$  defaults to 3-V mode after a POR. So, in a 5-V system care must be taken to ensure that  $V_{DD}$  is above the 5-V mode trip voltage after POR is released.

If the user requires 5-V mode and sets the LVI5OR3 bit after a power-on reset while the  $V_{DD}$  supply is not above the  $V_{TRIPR}$  for 5-V mode, the microcontroller unit (MCU) will immediately go into reset. The LVI in this case will hold the part in reset until either  $V_{DD}$  goes above the rising 5-V trip point,  $V_{TRIPR}$ , which will release reset or  $V_{DD}$  decreases to approximately 0 V which will re-trigger the power-on reset and reset the trip point to 3-V operation.



# Chapter 12 Input/Output Ports (PORTS)

# **12.1 Introduction**

Bidirectional input-output (I/O) pins form five parallel ports. All I/O pins are programmable as inputs or outputs. All individual bits within port A, port C, and port D are software configurable with pullup devices if configured as input port bits. The pullup devices are automatically and dynamically disabled when a port bit is switched to output mode.

#### NOTE

Connect any unused I/O pins to an appropriate logic level, either  $V_{DD}$  or  $V_{SS}$ . Although the I/O ports do not require termination for proper operation, termination reduces excess current consumption and the possibility of electrostatic damage.

Not all port pins are bonded out in all packages. Care sure be taken to make any unbonded port pins an output to reduce them from being floating inputs.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0				
\$0000	Port A Data Register (PTA)	Read: Write:	PTA7	PTA6	PTA5	PTA4	PTA3	PTA2	PTA1	PTA0				
	See page 124.	Reset:		Unaffected by reset										
Port B Data F \$0001	Port B Data Register (PTB)	Read: Write:	PTB7	PTB6	PTB5	PTB4	PTB3	PTB2	PTB1	PTB0				
	See page 126.	Reset:	Unaffected by reset											
\$0002	Port C Data Register (PTC)	Read:	0	PTC6	PTC5	PTC4	PTC3	PTC2	PTC1	PTC0				
		Write:		1100	1100	1104	1100	1102	1101	1100				
	See page 128.	Reset:	Unaffected by reset											
\$0003	Port D Data Register (PTD)	Read: Write:	PTD7	PTD6	PTD5	PTD4	PTD3	PTD2	PTD1	PTD0				
	See page 130.	Reset:		Unaffected by reset										
\$0004	Data Direction Register A (DDRA)	Read: Write:	DDRA7	DDRA6	DDRA5	DDRA4	DDRA3	DDRA2	DDRA1	DDRA0				
	See page 124.	Reset:	0	0	0	0	0	0	0	0				
				= Unimplem	ented									





Data direction register D (DDRD) does not affect the data direction of port D pins that are being used by the SPI module. However, the DDRD bits always determine whether reading port D returns the states of the latches or the states of the pins. See Table 12-5.

#### SS — Slave Select

The PTD0/SS pin is the slave select input of the SPI module. When the SPE bit is clear, or when the SPI master bit, SPMSTR, is set, the PTD0/SS pin is available for general-purpose I/O. When the SPI is enabled, the DDRB0 bit in data direction register B (DDRB) has no effect on the PTD0/SS pin.

## 12.5.2 Data Direction Register D

Data direction register D (DDRD) determines whether each port D pin is an input or an output. Writing a 1 to a DDRD bit enables the output buffer for the corresponding port D pin; a 0 disables the output buffer.



Figure 12-14. Data Direction Register D (DDRD)

#### DDRD7–DDRD0 — Data Direction Register D Bits

These read/write bits control port D data direction. Reset clears DDRD7–DDRD0, configuring all port D pins as inputs.

1 = Corresponding port D pin configured as output

0 = Corresponding port D pin configured as input

**NOTE** Avoid glitches on port D pins by writing to the port D data register before changing data direction register D bits from 0 to 1.

Figure 12-15 shows the port D I/O logic.



Figure 12-15. Port D I/O Circuit

### 13.3.3.1 Interrupt Status Register 1



Figure 13-6. Interrupt Status Register 1 (INT1)

#### IF6–IF1 — Interrupt Flags 6–1

These flags indicate the presence of interrupt requests from the sources shown in Table 13-2.

1 = Interrupt request present

0 = No interrupt request present

#### Bit 1 and Bit 0 — Always read 0

### 13.3.3.2 Interrupt Status Register 2



Figure 13-7. Interrupt Status Register 2 (INT2)

### IF14–IF7 — Interrupt Flags 14–7

These flags indicate the presence of interrupt requests from the sources shown in Table 13-2.

- 1 = Interrupt request present
- 0 = No interrupt request present

### 13.3.3.3 Interrupt Status Register 3



### Figure 13-8. Interrupt Status Register 3 (INT3)

### IF16–IF15 — Interrupt Flags 20–15

This flag indicates the presence of an interrupt request from the source shown in Table 13-2.

1 = Interrupt request present

0 = No interrupt request present

#### Bits 7–2 — Always read 0



#### 14.4.3.1 Character Length

The receiver can accommodate either 8-bit or 9-bit data. The state of the M bit in ESCI control register 1 (SCC1) determines character length. When receiving 9-bit data, bit R8 in ESCI control register 3 (SCC3) is the ninth bit (bit 8). When receiving 8-bit data, bit R8 is a copy of the eighth bit (bit 7).

#### 14.4.3.2 Character Reception

During an ESCI reception, the receive shift register shifts characters in from the RxD pin. The ESCI data register (SCDR) is the read-only buffer between the internal data bus and the receive shift register.

After a complete character shifts into the receive shift register, the data portion of the character transfers to the SCDR. The ESCI receiver full bit, SCRF, in ESCI status register 1 (SCS1) becomes set, indicating that the received byte can be read. If the ESCI receive interrupt enable bit, SCRIE, in SCC2 is also set, the SCRF bit generates a receiver CPU interrupt request.

#### 14.4.3.3 Data Sampling

The receiver samples the RxD pin at the RT clock rate. The RT clock is an internal signal with a frequency 16 times the baud rate. To adjust for baud rate mismatch, the RT clock is resynchronized at these times (see Figure 14-7):

- After every start bit
- After the receiver detects a data bit change from 1 to 0 (after the majority of data bit samples at RT8, RT9, and RT10 returns a valid 1 and the majority of the next RT8, RT9, and RT10 samples returns a valid 0)



To locate the start bit, data recovery logic does an asynchronous search for a logic 0 preceded by three 1s. When the falling edge of a possible start bit occurs, the RT clock begins to count to 16.

To verify the start bit and to detect noise, data recovery logic takes samples at RT3, RT5, and RT7. Table 14-2 summarizes the results of the start bit verification samples.



# 14.8.7 ESCI Baud Rate Register

The ESCI baud rate register (SCBR) together with the ESCI prescaler register selects the baud rate for both the receiver and the transmitter.

**NOTE** There are two prescalers available to adjust the baud rate. One in the ESCI baud rate register and one in the ESCI prescaler register.



Figure 14-17. ESCI Baud Rate Register (SCBR)

#### LINT — LIN Transmit Enable

This read/write bit selects the enhanced ESCI features for the local interconnect network (LIN) protocol as shown in Table 14-6.

#### LINR — LIN Receiver Bits

This read/write bit selects the enhanced ESCI features for the local interconnect network (LIN) protocol as shown in Table 14-6.

In LIN (version 1.2 and later) systems, the master node transmits a break character which will appear as 11.05-14.95 dominant bits to the slave node. A data character of 0x00 sent from the master might appear as 7.65-10.35 dominant bit times. This is due to the oscillator tolerance requirement that the slave node must be within  $\pm 15\%$  of the master node's oscillator. Because a slave node cannot know if it is running faster or slower than the master node (prior to synchronization), the LINR bit allows the slave node to differentiate between a 0x00 character of 10.35 bits and a break character of 11.05 bits. The break symbol length must be verified in software in any case, but the LINR bit serves as a filter, preventing false detections of break characters that are really 0x00 data characters.

LINT	LINR	М	Functionality
0	0	Х	Normal ESCI functionality
0	1	0	11-bit break detect enabled for LIN receiver
0	1	1	12-bit break detect enabled for LIN receiver
1	0	0	13-bit generation enabled for LIN transmitter
1	0	1	14-bit generation enabled for LIN transmitter
1	1	0	11-bit break detect/13-bit generation enabled for LIN
1	1	1	12-bit break detect/14-bit generation enabled for LIN

#### Table 14-6. ESCI LIN Control Bits



Enhanced Serial Communications Interface (ESCI) Module

# 14.9 ESCI Arbiter

The ESCI module comprises an arbiter module designed to support software for communication tasks as bus arbitration, baud rate recovery and break time detection. The arbiter module consists of an 9-bit counter with 1-bit overflow and control logic. The CPU can control operation mode via the ESCI arbiter control register (SCIACTL).

# 14.9.1 ESCI Arbiter Control Register



Figure 14-19. ESCI Arbiter Control Register (SCIACTL)

### AM1 and AM0 — Arbiter Mode Select Bits

These read/write bits select the mode of the arbiter module as shown in Table 14-12. Reset clears AM1 and AM0.

#### Table 14-12. ESCI Arbiter Selectable Modes

AM[1:0]	ESCI Arbiter Mode
0 0	Idle / counter reset
0 1	Bit time measurement
10	Bus arbitration
1 1	Reserved / do not use

### ALOST — Arbitration Lost Flag

This read-only bit indicates loss of arbitration. Clear ALOST by writing a 0 to AM1. Reset clears ALOST.

### ACLK — Arbiter Counter Clock Select Bit

This read/write bit selects the arbiter counter clock source. Reset clears ACLK.

- 1 = Arbiter counter is clocked with one half of the ESCI input clock generated by the ESCI prescaler
- 0 = Arbiter counter is clocked with the bus clock divided by four

### NOTE

For ACLK = 1, the arbiter input clock is driven from the ESCI prescaler. The prescaler can be clocked by either the bus clock or CGMXCLK depending on the state of the ESCIBDSRC bit in CONFIG2.

### AFIN— Arbiter Bit Time Measurement Finish Flag

This read-only bit indicates bit time measurement has finished. Clear AFIN by writing any value to SCIACTL. Reset clears AFIN.

- 1 = Bit time measurement has finished
- 0 = Bit time measurement not yet finished

#### Timer Interface Module (TIM)



1. Ports are software configurable with pullup device if input port.

2. Higher current drive port pins

3. Pin contains integrated pullup device

### Figure 18-2. Block Diagram Highlighting TIM Blocks and Pins





# 18.9.1 TIM Status and Control Register

The TIM status and control register (TSC):

- Enables TIM overflow interrupts
- Flags TIM overflows
- Stops the TIM counter
- Resets the TIM counter
- Prescales the TIM counter clock





Figure 18-5. TIM Status and Control Register (TSC)

#### TOF — TIM Overflow Flag Bit

This read/write flag is set when the TIM counter reaches the modulo value programmed in the TIM counter modulo registers. Clear TOF by reading the TIM status and control register when TOF is set and then writing a 0 to TOF. If another TIM overflow occurs before the clearing sequence is complete, then writing 0 to TOF has no effect. Therefore, a TOF interrupt request cannot be lost due to inadvertent clearing of TOF. Reset clears the TOF bit. Writing a logic 1 to TOF has no effect.

1 = TIM counter has reached modulo value

0 = TIM counter has not reached modulo value

#### **TOIE** — **TIM** Overflow Interrupt Enable Bit

This read/write bit enables TIM overflow interrupts when the TOF bit becomes set. Reset clears the TOIE bit.

1 = TIM overflow interrupts enabled

0 = TIM overflow interrupts disabled

#### TSTOP — TIM Stop Bit

This read/write bit stops the TIM counter. Counting resumes when TSTOP is cleared. Reset sets the TSTOP bit, stopping the TIM counter until software clears the TSTOP bit.

1 = TIM counter stopped

0 = TIM counter active

#### NOTE

Do not set the TSTOP bit before entering wait mode if the TIM is required to exit wait mode.

#### TRST — TIM Reset Bit

Setting this write-only bit resets the TIM counter and the TIM prescaler. Setting TRST has no effect on any other registers. Counting resumes from \$0000. TRST is cleared automatically after the TIM counter is reset and always reads as 0. Reset clears the TRST bit.

1 = Prescaler and TIM counter cleared

0 = No effect



#### Monitor ROM (MON)



#### Table 19-8. RUN (Run User Program) Command

The MCU executes the SWI and PSHH instructions when it enters monitor mode. The RUN command tells the MCU to execute the PULH and RTI instructions. Before sending the RUN command, the host can modify the stacked CPU registers to prepare to run the host program. The READSP command returns the incremented stack pointer value, SP + 1. The high and low bytes of the program counter are at addresses SP + 5 and SP + 6.

	SP
HIGH BYTE OF INDEX REGISTER	SP + 1
CONDITION CODE REGISTER	SP + 2
ACCUMULATOR	SP + 3
LOW BYTE OF INDEX REGISTER	SP + 4
HIGH BYTE OF PROGRAM COUNTER	SP + 5
LOW BYTE OF PROGRAM COUNTER	SP + 6
	SP + 7

Figure 19-17. Stack Pointer at Monitor Mode Entry

### 19.3.2 Security

A security feature discourages unauthorized reading of FLASH locations while in monitor mode. The host can bypass the security feature at monitor mode entry by sending eight security bytes that match the bytes at locations \$FFF6–\$FFFD. Locations \$FFF6–\$FFFD contain user-defined data.

#### NOTE

Do not leave locations \$FFF6-\$FFFD blank. For security reasons, program locations \$FFF6-\$FFFD even if they are not used for vectors.

During monitor mode entry, the MCU waits after the power-on reset for the host to send the eight security bytes on pin PTA0. If the received bytes match those at locations \$FFF6-\$FFFD, the host bypasses the security feature and can read all FLASH locations and execute code from FLASH. Security remains bypassed until a power-on reset occurs. If the reset was not a power-on reset, security remains bypassed and security code entry is not required. See Figure 19-18.



# 20.6 3.3-Vdc Electrical Characteristics

Characteristic <sup>(1)</sup>	Symbol	Min	Typ <sup>(2)</sup>	Мах	Unit
Output high voltage					
$(I_{Load} = -0.6 \text{ mA})$ all I/O pins	V <sub>OH</sub>	V <sub>DD</sub> – 0.3	—	—	V
$(I_{Load} = -4.0 \text{ mA}) \text{ all I/O pins}$	V <sub>OH</sub>	V <sub>DD</sub> – 1.0	—	—	V
$(I_{Load} = -10.0 \text{ mA})$ pins PTC0–PTC4 only	V <sub>OH</sub>	V <sub>DD</sub> – 1.0	_	—	V
Maximum combined I <sub>OH</sub> for port PTA7–PTA3,	I <sub>OH1</sub>	—	_	30	mΔ
port PTC0–PTC1, port E, port PTD0–PTD3				00	117.
Maximum combined I <sub>OH</sub> for port PTA2–PTA0,	I <sub>OH2</sub>	—	—	30	mA
port B, port PTC2–PTC6, port PTD4–PTD7					
Maximum total I <sub>OH</sub> for all port pins	ЮНТ		—	60	mA
Output low voltage					
(I <sub>Load</sub> = 1.6 mA) all I/O pins	V <sub>OL</sub>	—	—	0.3	V
(I <sub>Load</sub> = 10 mA) all I/O pins	V <sub>OL</sub>	—	—	1.0	V
(I <sub>Load</sub> = 20 mA) pins PTC0–PTC4 only	V <sub>OL</sub>	_	_	0.8	v
Maximum combined I <sub>OH</sub> for port PTA7–PTA3,	I <sub>OL1</sub>	_	_	30	mA
port PTC0–PTC1, port E, port PTD0–PTD3					
Maximum combined I <sub>OH</sub> for port PTA2–PTA0,	I <sub>OL2</sub>	—	—	30	mA
port B, port PTC2–PTC6, port PTD4–PTD7					
Maximum total I <sub>OL</sub> for all port pins	IOLT	—	—	60	mA
Input high voltage	Vill	0.7 × Vpp	_	Voo	v
All ports, IRQ, RST, OSC1		00		66	_
Input low voltage	VII	V <sub>SS</sub>	_	$0.3 \times V_{DD}$	v
All ports, IRQ, RST, OSC1					
V <sub>DD</sub> supply current					
Run <sup>(3)</sup>		—	8	12	mA
Wait <sup>(4)</sup>		—	3	6	mA
Stop <sup>(5)</sup>					
25°C	I <sub>DD</sub>	_	2	_	μА
25°C with TBM enabled <sup>(6)</sup>		_	12	_	μΑ
25°C with LVI and TBM enabled <sup>(6)</sup>		—	200	—	μΑ
–40°C to 125°C with TBM enabled <sup>(6)</sup>		—	30	—	μA
–40°C to 125°C with LVI and TBM enabled <sup>(6)</sup>		—	300	—	μA
DC injection current, all ports	I <sub>INJ</sub>	-2		+2	mA
Total dc current injection (sum of all I/O)	I <sub>INJTOT</sub>	-25		+25	mA
I/O ports Hi-Z leakage current <sup>(7)</sup>	Ι <sub>ΙL</sub>	-10		+10	μA
Input current	l <sub>ln</sub>	-1	—	+1	μA
Pullup resistors (as input only)					
Ports PTA7/KBD7–PTA0/KBD0, PTC6–PTC0,	R <sub>PU</sub>	20	45	65	kΩ
PTD7/T2CH1-PTD0/SS					
Capacitance	C <sub>Out</sub>		—	12	~ <b>~</b>
Ports (as input or output)	C <sub>In</sub>	—	—	8	μг

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